ANSYS Collaborates With Intel To Spur Customer Innovation

March 12, 2015

PITTSBURGH, March 12, 2015 /PRNewswire/ -- Engineers using the newly released ANSYS® 16.0 in combination with powerful Intel® Xeon® technology can realize a 300 percent decrease in solution time – helping them to innovate and bring new products to market faster.

The ANSYS and Intel partnership ensures that simulation engineers performing structural analysis can expect seamless high-performance computing (HPC) operations with multi-core Xeon E5 v3 processors and many-core Xeon Phi™coprocessors. The result is the ability to run multiple, incredibly large simulations rapidly — which is becoming standard when developing today's innovative products.

"ANSYS 16.0 provides the accuracy, efficiency and robustness required for engineers to generate proven designs as quickly as possible," said Wim Slagter, lead product manager for HPC, at ANSYS. "We've worked in tandem with Intel to optimize ANSYS software for the architectural changes in the new processor generation, so customers can leverage HPC technology to incorporate more-complex models, whether using finer meshes or investigating nonlinear behavior."

Because simulation times can be reduced with Xeon processors and coprocessors, engineering departments can run more simulations in a given period of time — offering the ability to look into more design variables for developing better and higher-quality products without affecting time to market.

ANSYS is the first commercial engineering simulation software provider supporting Xeon Phi technology. ANSYS 16.0's structural mechanics suite supports Xeon Phi with shared-memory and distributed-memory parallelism for both the Linux and Windows platforms. Virtually all ANSYS users — including those who have access to clusters in which each compute node contains one or more coprocessors — can accelerate structural mechanics simulations using Xeon Phi coprocessors. For example, upgrading from the previous generation Xeon processor and adding one Xeon Phi coprocessor results in a decreased time to solution by a factor of 3.1 for ANSYS Mechanical ™simulations.

"Dramatic performance increases can transform entire engineering workflows," said Frank Soqui, general manager, Technical Compute Cloud and Client at Intel Corporation. "The collaboration between Intel and ANSYS has delivered just that, tremendous new performance levels, without altering the end-user experience or complicating the IT environment for great price/performance results. We're excited to see ANSYS continuing its leadership in delivering structural analysis capabilities to market, addressing the technical compute needs of Windows users with Intel Xeon processors and Xeon Phi coprocessors."

*Based on Intel internal testing of ANSYS Mechanical 16.0, workload V16ln-2 DMP on 2 cores, comparing an Intel® Xeon® E5-2697 v2 system to an Intel® Xeon® E5-2697v3 system featuring an Intel® Xeon Phi™ 7120P coprocessor on the same workload.

About ANSYS, Inc.
ANSYS brings clarity and insight to customers' most complex design challenges through fast, accurate and reliable engineering simulation. Our technology enables organizations — no matter their industry — to predict with confidence that their products will thrive in the real world. Customers trust our software to help ensure product integrity and drive business success through innovation. Founded in 1970, ANSYS employs over 2700 professionals, many of them experts in engineering fields such as finite element analysis, computational fluid dynamics, electronics and electromagnetics, embedded software, system simulation and design optimization. Headquartered south of Pittsburgh, U.S.A., ANSYS has more than 75 strategic sales locations throughout the world with a network of channel partners in 40+ countries. Visit www.ansys.com for more information.

ANSYS also has a strong presence on the major social channels. To join the simulation conversation, please visit: www.ansys.com/Social@ANSYS

ANSYS and any and all ANSYS, Inc. brand, product, service and feature names, logos and slogans are registered trademarks or trademarks of ANSYS, Inc. or its subsidiaries in the United States or other countries. All other brand, product, service and feature names or trademarks are the property of their respective owners.

ANSS-T

Contact	Media	Tom Smithyman 724.820.4340 tom.smithyman@ansys.com

	Investors	Annette Arribas, CTP 724.820.3700 annette.arribas@ansys.com

Logo - http://photos.prnewswire.com/prnh/20130430/NE03388LOGO

To view the original version on PR Newswire, visit:http://www.prnewswire.com/news-releases/ansys-and-intel-spur-customer-innovation-300049148.html

SOURCE ANSYS, Inc.